

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 1 of 2

Complete if Known

Application Number	Not Yet Assigned 10/767764
Filing Date	January 29, 2004
First Named Inventor	Hineman et al.
Group Art Unit	Unknown 2826
Examiner Name	Unknown Kevin Quinto
Attorney Docket Number	2269-5925US (03-0290.00/US)

**U.S. PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code <sup>2</sup> (if known)			
KQ		US-6,204,192 B1	03/20/2001	Zhao et al.	
		US- 6,319,842 B1	11/20/2001	Khosla et al.	
		US- 2001/0049181 A1	12/06/2001	Rathi et al.	
		US- 2002/0098685 A1	07/25/2002	Sophie et al.	
		US- 2802/0167089 A1	11/14/2002	Ahn et al.	
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KQ		US- 6,534,397 B1	03/18/2003	Okada et al.	
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> - Number <sup>4</sup> - Kind Code <sup>5</sup> (if known)				
KQ		WO 99/60601	11/25/1999	Cohen et al.		

Examiner Signature

Kevin Quinto

Date Considered

6/26/05

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached.

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Examiner Name	Unknown - Kevin Quinto
Attorney Docket Number	2269-592511S (03-0290 00/11S)

**OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
KL		EISENBRAUN et al., "Selective and Blanket Low Temperature Copper CVD for Multilevel Metallization," Materials Research Society Conference Proceedings, ULSI VII, 397 401 (1992).	
		KLAUS, J. W. et al., "Atomic Layer Deposition of Tungsten Nitride Films Using Sequential Surface Reaction," Journal of Electrochemical Soc., 147:3, 1175 81 (2000).	
		KALOYEROS et al., "Blanket and Selective Copper CVD From Cu(fod) <sub>2</sub> For Multilevel Metallization," Mat. Res. Soc. Symp. Proc., Vol. 181 (1990).	
		SHACHAM-DIAMAND et al., "Copper Electroless Deposition Technology for Ultra Large Scale Integration (ULSI) Metallization," Microelectronic Engineering, Vol. 33, pp. 47 48 (1997).	
KL		ZHENG et al., "Polymer Residue chemical Composition Analysis and its Effect on Via Contact Resistance in Dual Damascene Copper Interconnects Process Integration," Microelectronics Journal, Vol. 34 (2003), pp. 109-113.	

Examiner  
Signature

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